# Few External Components Reliable and Flexible GreenLine™ Very High Voltage PWM Controller

The MC44608 is a high performance voltage mode controller designed for off–line converters. This high voltage circuit that integrates the start–up current source and the oscillator capacitor, requires few external components while offering a high flexibility and reliability.

The device also features a very high efficiency stand-by management consisting of an effective Pulsed Mode operation. This technique enables the reduction of the stand-by power consumption to approximately 1W while delivering 300mW in a 150W SMPS.

- Integrated Start-Up Current Source
- Lossless Off–Line Start–Up
- Direct Off-Line Operation
- Fast Start-Up

### **General Features**

- Flexibility
- Duty Cycle Control
- Undervoltage Lockout with Hysteresis
- On Chip Oscillator Switching Frequency 40, or 75kHz
- Secondary Control with Few External Components

### **Protections**

- Maximum Duty Cycle Limitation
- Cycle by Cycle Current Limitation
- Demagnetization (Zero Current Detection) Protection
- "Over VCC Protection" Against Open Loop
- Programmable Low Inertia Over Voltage Protection Against Open Loop
- Internal Thermal Protection

### **GreenLine™ Controller**

- Pulsed Mode Techniques for a Very High Efficiency Low Power Mode
- Lossless Startup
- Low dV/dT for Low EMI Radiations

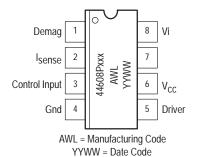


http://onsemi.com



DIP-8 P SUFFIX CASE 626

# PIN CONNECTIONS AND MARKING DIAGRAM

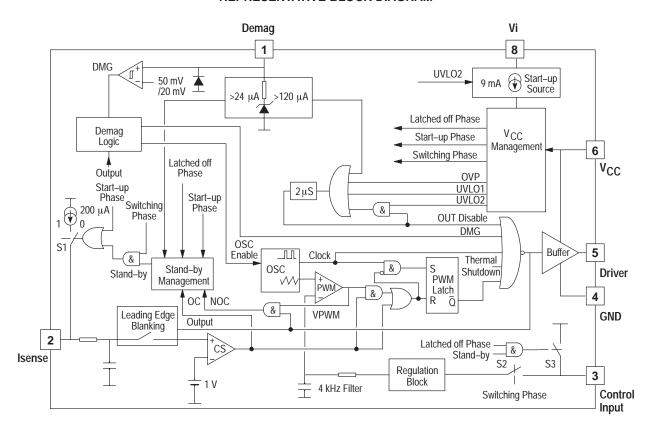


(Top View)

### ORDERING INFORMATION

Device	Switching Frequency	Package	Shipping
MC44608P40	40kHz	Plastic DIP-8	50 / Rail
MC44608P75	75kHz	Plastic DIP-8	50 / Rail

### REPRESENTATIVE BLOCK DIAGRAM



### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Total Power Supply Current	lcc	30	mA
Output Supply Voltage with Respect to Ground	VCC	16	V
All Inputs except Vi	Vinputs	-1.0 to +16	V
Line Voltage	V <sub>i</sub>	500	V
Power Dissipation and Thermal Characteristics  Maximum Power Dissipation at T <sub>A</sub> = 85°C  Thermal Resistance, Junction–to–Air	P <sub>D</sub> R <sub>θJA</sub>	600 100	mW °C/W
Operating Junction Temperature	TJ	150	°C
Operating Ambient Temperature	TA	-25 to +85	°C

### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Min	Тур	Max	Unit
OUTPUT SECTION				<u> </u>	
Output Resistor Sink Resistance Source Resistance	R <sub>OL</sub> ROH	5.0	8.5 15	15	Ω
Output Voltage Rise Time (from 3 V up to 9 V) (1)	t <sub>r</sub>		50		ns
Output Voltage Falling Edge Slew–Rate (from 9 V down to 3 V) (1)	tf		50		ns
CONTROL INPUT SECTION					
Duty Cycle @ Ipin3 = 2.5 mA	d <sub>2mA</sub>			2.0	%
Duty Cycle @ Ipin3 = 1.0 mA	d <sub>1m</sub> A	36	43	48	%
Control Input Clamp Voltage (Switching Phase) @ Ipin3 = -1.0 mA		4.75	5.0	5.25	V
Latched Phase Control Input Voltage (Stand-by) @ Ipin3 = +500 μA	V <sub>LP-stby</sub>	3.4	3.9	4.3	V
Latched Phase Control Input Voltage (Stand-by) @ Ipin3 = +1.0 mA	V <sub>LP-stby</sub>	2.4	3.0	3.7	V
CURRENT SENSE SECTION					
Maximum Current Sense Input Threshold	V <sub>CS-th</sub>	0.95	1.0	1.05	V
Input Bias Current	I <sub>B-cs</sub>	-1.8		1.8	μΑ
Stand-By Current Sense Input Current	ICS-stby	180	200	220	μΑ
Start-up Phase Current Sense Input Current	ICS-stup	180	200	220	μΑ
Propagation Delay (Current Sense Input to Output @ V <sub>TH</sub> T MOS = 3 V)	T <sub>PLH</sub> (In/Out)		220		ns
Leading Edge Blanking Duration MC44608P40	T <sub>LEB</sub>		480		ns
Leading Edge Blanking Duration MC44608P75	T <sub>LEB</sub>		250		ns
Leading Edge Blanking Duration MC44608P100	T <sub>LEB</sub>		200		ns
Leading Edge Blanking + Propagation Delay MC44608P40	T <sub>DLY</sub>	500	680	900	ns
Leading Edge Blanking + Propagation Delay MC44608P75	T <sub>DLY</sub>	370	470	570	ns
Leading Edge Blanking + Propagation Delay MC44608P100	T <sub>DLY</sub>		400		ns
OSCILLATOR SECTION	•		•	•	
Normal Operation Frequency MC44608P40	fosc	36	40	44	kHz
Normal Operation Frequency MC44608P75	fosc	68	75	82	kHz
Normal Operation Frequency MC44608P100	fosc		100		kHz
Maximum Duty Cycle @ f = f <sub>OSC</sub>	d <sub>max</sub>	78	82	86	%
OVERVOLTAGE SECTION					
Quick OVP Input Filtering (R <sub>demag</sub> = 100 kΩ)	T <sub>filt</sub>		250		ns
Propagation Delay (I <sub>demag</sub> > I <sub>ovp</sub> to output low)	TPHL(In/Out)		2.0		μs
Quick OVP Current Threshold	lovp	105	120	140	μА
Protection Threshold Level on V <sub>CC</sub>	VCC-OVP	14.8	15.3	15.8	V
Minimum Gap Between V <sub>CC</sub> –OVP and V <sub>stup</sub> –th	VCC-OVP - V <sub>stup</sub>	1.0			V

### NOTES:

(1) This parameter is measured using 1.0 nF connected between the output and the ground.

**ELECTRICAL CHARACTERISTICS** ( $V_{CC} = 12 \text{ V}$ , for typical values  $T_A = 25^{\circ}\text{C}$ , for min/max values  $T_A = -25^{\circ}\text{C}$  to +85°C unless otherwise noted) (Note 1)

Characteristic	Symbol	Min	Тур	Max	Unit	
DEMAGNETIZATION DETECTION SECTION (Note 2)	<u> </u>		1		<u> </u>	
Demag Comparator Threshold (Vpin1 increasing)	V <sub>dmg-th</sub>	30	50	69	mV	
Demag Comparator Hysteresis (Note 3)	H <sub>dmg</sub>		30		mV	
Propagation Delay (Input to Output, Low to High)	tPHL(In/Out)		300		ns	
Input Bias Current (V <sub>demag</sub> = 50 mV)		I <sub>dem-Ib</sub>	-0.6			μΑ
Negative Clamp Level (I <sub>demag</sub> = −1 mA)		V <sub>cl-neg-dem</sub>	-0.9	-0.7	-0.4	V
Positive Clamp Level @ I <sub>demag</sub> = 125 μA	V <sub>cl</sub> -pos- dem-H	2.05	2.3	2.8	V	
Positive Clamp Level @ I <sub>demag</sub> = 25 μA	V <sub>cl-pos-</sub> dem-L	1.4	1.7	1.9	V	
OVERTEMPERATURE SECTION						
Trip Level Over Temperature		T <sub>high</sub>		160		°C
Hysteresis		T <sub>hyst</sub>		30		°C
STAND-BY MAXIMUM CURRENT REDUCTION SECTI	ON					
Normal Mode Recovery Demag Pin Current Threshold		I <sub>dem</sub> -NM	20	25	30	μΑ
K FACTORS SECTION FOR PULSED MODE OPERATI	ON					
ICCS / Istup	MC44608P40	10 x K1	2.4	2.9	3.8	_
ICCS / Istup	MC44608P75	10 x K1	2.8	3.3	4.2	_
ICCS / Istup	MC44608P100	10 x K1		3.5		_
ICCL / Istup		10 <sup>3</sup> x K2	46	52	63	_
(V <sub>stup</sub> – UVLO2) / (V <sub>stup</sub> – UVLO1)		10 <sup>2</sup> x K <sub>sstup</sub>	1.8	2.2	2.6	_
(UVLO1 – UVLO2) / (V <sub>stup</sub> – UVLO1)		10 <sup>2</sup> x K <sub>sl</sub>	90	120	150	_
I <sub>CS</sub> / V <sub>csth</sub>		10 <sup>6</sup> x Y <sub>cstby</sub>	175	198	225	_
Demag ratio I <sub>ovp</sub> / I <sub>dem</sub> NM	Demag ratio I <sub>ovp</sub> / I <sub>dem</sub> NM		3.0	4.7	5.5	_
$(V3_{1 \text{ mA}} - V3_{0.5 \text{ mA}}) / (1 \text{ mA} - 0.5 \text{ mA})$	R3		1800		Ω	
V <sub>control</sub> Latch–off		V3		4.8		V
SUPPLY SECTION						
Minimum Start-up Voltage		Vi <sub>low</sub>			50	V
V <sub>CC</sub> Start-up Voltage		V <sub>stup-th</sub>	12.5	13.1	13.8	V
Output Disabling V <sub>CC</sub> Voltage After Turn On		V <sub>uvlo1</sub>	9.5	10	10.5	V
Hysteresis (V <sub>stup-th</sub> - V <sub>uvlo1</sub> )		H <sub>stup-uvlo1</sub>		3.1		V
V <sub>CC</sub> Undervoltage Lockout Voltage		V <sub>uvlo2</sub>	6.2	6.6	7.0	V
Hysteresis (V <sub>uvlo1</sub> – V <sub>uvlo2</sub> )		H <sub>uvlo1-uvlo2</sub>		3.4		V
Absolute Normal Condition $V_{CC}$ Start Current @ ( $V_i = 100 \text{ V}$ ) and ( $V_{CC} = 9 \text{ V}$ )		-(ICC)	7.0	9.5	12.8	mA
Switching Phase Supply Current (no load)  MC44608P4  MC44608P7  MC44608P1		Iccs	2.0 2.4 –	2.6 3.2 3.4	3.6 4.0 –	mA
Latched Off Phase Supply Current		ICC-latch	0.3	0.5	0.68	mA
Hiccup Mode Duty Cycle (no load)		δHiccup		10		%

### NOTES:

<sup>(1)</sup> Adjust  $V_{CC}$  above the start—up threshold before setting to 12 V. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

<sup>(2)</sup> This function can be inhibited by connecting pin 1 to GND.

<sup>(3)</sup> Guaranteed by design (non tested)

### PIN FUNCTION DESCRIPTION

Pin	Name	Description
1	Demag	The Demag pin offers 3 different functions: Zero voltage crossing detection (50mV), 24μA current detection and 120μA current detection. The 24μA level is used to detect the secondary reconfiguration status and the 120μA level to detect an Over Voltage status called Quick OVP.
2	I <sub>sense</sub>	The Current Sense pin senses the voltage developed on the series resistor inserted in the source of the power MOSFET. When I <sub>Sense</sub> reaches 1V, the Driver output (pin 5) is disabled. This is known as the Over Current Protection function. A 200µA current source is flowing out of the pin 3 during the start—up phase and during the switching phase in case of the Pulsed Mode of operation. A resistor can be inserted between the sense resistor and the pin 3, thus a programmable peak current detection can be performed during the SMPS stand—by mode.
3	Control Input	A feedback current from the secondary side of the SMPS via the opto–coupler is injected into this pin. A resistor can be connected between this pin and GND to allow the programming of the Burst duty cycle during the Stand–by mode.
4	Ground	This pin is the ground of the primary side of the SMPS.
5	Driver	The current and slew rate capability of this pin are suited to drive Power MOSFETs.
6	Vcc	This pin is the positive supply of the IC. The driver output gets disabled when the voltage becomes higher than 15V and the operating range is between 6.6V and 13V. An intermediate voltage level of 10V creates a disabling condition called Latched Off phase.
7		This pin is to provide isolation between the Vi pin 8 and the V <sub>CC</sub> pin 6.
8	Vi	This pin can be directly connected to a 500V voltage source for start–up function of the IC. During the Start–up phase a 9 mA current source is internally delivered to the V <sub>CC</sub> pin 6 allowing a rapid charge of the V <sub>CC</sub> capacitor. As soon as the IC starts–up, this current source is disabled.

### **OPERATING DESCRIPTION**

### Regulation

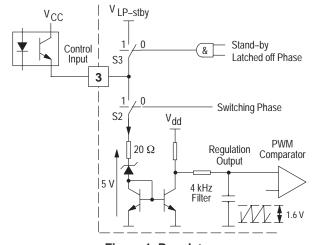


Figure 1. Regulator

The pin 3 senses the feedback current provided by the opto coupler. During the switching phase the switch S2 is closed and the shunt regulator is accessible by the pin 3. The shunt regulator voltage is typically 5V. The dynamic resistance of the shunt regulator represented by the zener diode is  $20\Omega$ . The gain of the Control input is given on Figure 10 which shows the duty cycle as a function of the current injected into the pin 3.

A 4kHz filter network is inserted between the shunt regulator and the PWM comparator to cancel the high frequency residual noise.

The switch S3 is closed in Stand-by mode during the Latched Off Phase while the switch S2 remains open. (See section PULSED MODE DUTY CYCLE CONTROL).

The resistor Rdpulsed (Rduty cycle burst) has no effect on the regulation process. This resistor is used to determine the burst duty cycle described in the chapter "Pulsed Duty Cycle Control" on page 8.

### **PWM Latch**

The MC44608 works in voltage mode. The on–time is controlled by the PWM comparator that compares the oscillator sawtooth with the regulation block output (refer to the block diagram on page 2).

The PWM latch is initialized by the oscillator and is reset by the PWM comparator or by the current sense comparator in case of an over current. This configuration ensures that only a single pulse appears at the circuit output during an oscillator cycle.

### **Current Sense**

The inductor current is converted to a positive voltage by inserting a ground reference sense resistor R<sub>Sense</sub> in series with the power switch.

The maximum current sense threshold is fixed at 1V. The peak current is given by the following equation:

$$lpk_{max} = \frac{1}{R_{sense}(\Omega)}(A)$$

In stand–by mode, this current can be lowered as due to the activation of a  $200\mu A$  current source:

$$lpk_{max-stby} = \frac{1 - (R_{CS}(k\Omega) \times 0, 2)}{R_{sense}(\Omega)}(A)$$

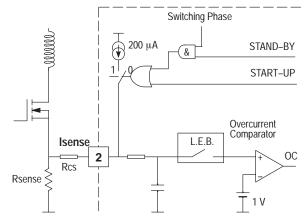


Figure 2. Current Sense

The current sense input consists of a filter ( $6k\Omega$ , 4pF) and of a leading edge blanking. Thanks to that, this pin is not sensitive to the power switch turn on noise and spikes and practically in most applications, no filtering network is required to sense the current.

Finally, this pin is used:

- as a protection against over currents (Isense > I)
- as a reduction of the peak current during a Pulsed Mode switching phase.

The overcurrent propagation delay is reduced by producing a sharp output turn off (high slew rate). This results in an abrupt output turn off in the event of an over current and in the majority of the pulsed mode switching sequense.

### **Demagnetization Section**

The MC44608 demagnetization detection consists of a comparator designed to compare the V<sub>CC</sub> winding voltage to a reference that is typically equal to 50mV.

This reference is chosen low to increase effectiveness of the demagnetization detection even during start—up.

A latch is incorporated to turn the demagnetization block output into a low level as soon as a voltage less than 50 mV is detected, and to keep it in this state until a new pulse is generated on the output. This avoids any ringing on the input signal which may alter the demagnetization detection.

For a higher safety, the demagnetization block output is also directly connected to the output, which is disabled during the demagnetization phase.

The demagnetization pin is also used for the quick, programmable OVP. In fact, the demagnetization input current is sensed so that the circuit output is latched off when this current is detected as higher than 120µA.

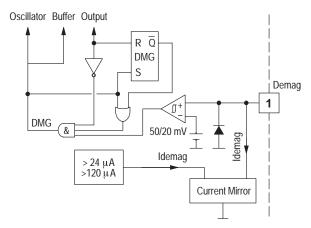


Figure 3. Demagnetization Block

This function can be inhibited by grounding it but in this case, the quick and programmable OVP is also disabled.

### Oscillator

The MC44608 contains a fixed frequency oscillator. It is built around a fixed value capacitor CT succesively charged and discharged by two distinct current sources ICH and IDCH. The window comparator senses the CT voltage value and activates the sources when the voltage is reaching the 2.4V/4V levels.

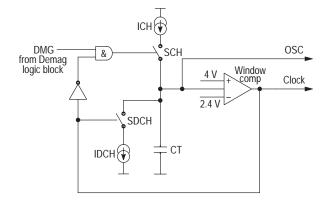
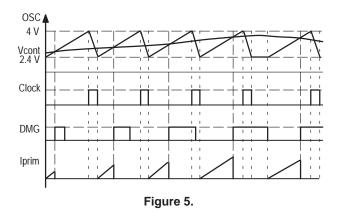


Figure 4. Oscillator Block

The complete demagnetization status DMG is used to inhibit the recharge of the CT capacitor. Thus in case of incomplete transformer demagnetization the next switching cycle is postpone until the DMG signal appears. The oscillator remains at 2.4V corresponding to the sawtooth valley voltage. In this way the SMPS is working in the so called SOPS mode (Self Oscillating Power Supply). In that case the effective switching frequency is variable and no longer depends on the oscillator timing but on the external working conditions (Refer to DMG signal in the Figure 5).



The OSC and Clock signals are provided according to the Figure 5. The Clock signals correspond to the CT capacitor discharge. The bottom curve represents the current flowing in the sense resistor Rcs. It starts from zero and stops when the sawtooth value is equal to the control voltage Vcont. In this way the SMPS is regulated with a voltage mode control.

### **Overvoltage Protection**

The MC44608 offers two OVP functions:

- a fixed function that detects when  $V_{CC}$  is higher than 15.4 V
- a programmable function that uses the demag pin. The current flowing into the demag pin is mirrored and compared to the reference current Iovp (120 $\mu$ A). Thus this OVP is quicker as it is not impacted by the  $V_{CC}$  inertia and is called QOVP.

In both cases, once an OVP condition is detected, the output is latched off until a new circuit START-UP.

### Start-up Management

The Vi pin 8 is directly connected to the HV DC rail Vin. This high voltage current source is internally connected to the V<sub>CC</sub> pin and thus is used to charge the V<sub>CC</sub> capacitor. The V<sub>CC</sub> capacitor charge period corresponds to the Start–up phase. When the V<sub>CC</sub> voltage reaches 13V, the high voltage 9mA current source is disabled and the device starts working. The device enters into the switching phase.

It is to be noticed that the maximum rating of the Vi pin 8 is 700V. ESD protection circuitry is not currently added to this pin due to size limitations and technology constraints. Protection is limited by the drain–substrate junction in avalanche breakdown. To help increase the application safety against high voltage spike on that pin it is possible to insert a small wattage  $1k\Omega$  series resistor between the Vin rail and pin 8.

The Figure 6 shows the V<sub>CC</sub> voltage evolution in case of no external current source providing current into the V<sub>CC</sub> pin during the switching phase. This case can be encountered in SMPS when the self supply through an auxiliary winding is not present (strong overload on the SMPS output for example). The Figure 16 also depicts this working configuration.

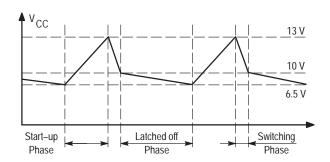


Figure 6. Hiccup Mode

In case of the hiccup mode, the duty cycle of the switching phase is in the range of 10%.

### **Mode Transition**

The LW latch Figure 7 is the memory of the working status at the end of every switching sequence.

Two different cases must be considered for the logic at the termination of the SWITCHING PHASE:

- 1. No Over Current was observed
- 2. An Over Current was observed

These 2 cases are corresponding to the signal labelled NOC in case of "No Over Current" and "OC" in case of Over Current. So the effective working status at the end of the ON time memorized in LW corresponds to Q=1 for no over current and O=0 for over current.

This sequence is repeated during the Switching phase. Several events can occur:

- 1. SMPS switch OFF
- 2. SMPS output overload
- 3. Transition from Normal to Pulsed Mode
- 4. Transition from Pulsed Mode to Normal Mode

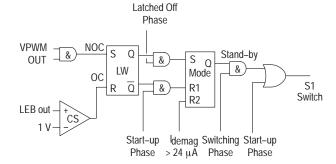


Figure 7. Transition Logic

### • 1. SMPS SWITCH OFF

When the mains is switched OFF, so long as the bulk electrolithic bulk capacitor provides energy to the SMPS, the controller remains in the switching phase. Then the peak current reaches its maximum peak value, the switching frequency decreases and all the secondary voltages are reduced. The  $V_{CC}$  voltage is also reduced. When  $V_{CC}$  is equal to 10V, the SMPS stops working.

### · 2. Overload

In the hiccup mode the 3 distinct phases are described as follows (refer to Figure 6):

The SWITCHING PHASE: The SMPS output is low and the regulation block reacts by increasing the ON time (dmax = 80%). The OC is reached at the end of every switching cycle. The LW latch (Figure 7) is reset before the VPWM signal appears. The SMPS output voltage is low. The V<sub>CC</sub> voltage cannot be maintained at a normal level as the auxiliary winding provides a voltage which is also reduced in a ratio similar to the one on the output (i.e. Vout nominal / Vout short—circuit). Consequently the V<sub>CC</sub> voltage is reduced at an operating rate given by the combination V<sub>CC</sub> capacitor value together with the I<sub>CC</sub> working consumption (3.2mA) according to the equation 2. When V<sub>CC</sub> crosses 10V the WORKING PHASE gets terminated. The LW latch remains in the reset status.

The LATCHED-OFF PHASE: The V<sub>CC</sub> capacitor voltage continues to drop. When it reaches 6.5V this phase is terminated. Its duration is governed by equation 3.

The START–UP PHASE is reinitiated. The high voltage start–up current source ( $-I_{CC1} = 9mA$ ) is activated and the MODE latch is reset. The  $V_{CC}$  voltage ramps up according to the equation 1. When it reaches 13V, the IC enters into the SWITCHING PHASE.

The NEXT SWITCHING PHASE: The high voltage current source is inhibited, the MODE latch (Q=0) activates the NORMAL mode of operation. Figure 2 shows that no current is injected out pin 2. The over current sense level corresponds to 1V.

As long as the overload is present, this sequence repeats. The SWITCHING PHASE duty cycle is in the range of 10%.

### • 3. Transition from Normal to Pulsed Mode

In this sequence the secondary side is reconfigured (refer to the typical application schematic on page 13). The high voltage output value becomes lower than the NORMAL mode regulated value. The TL431 shunt regulator is fully OFF. In the SMPS stand–by mode all the SMPS outputs are lowered except for the low voltage output that supply the wake–up circuit located at the isolated side of the power supply. In that mode the secondary regulation is performed by the zener diode connected in parallel to the TL431.

The secondary reconfiguration status can be detected on the SMPS primary side by measuring the voltage level present on the auxiliary winding Laux. (Refer to the Demagnetization Section). In the reconfigured status, the Laux voltage is also reduced. The V<sub>CC</sub> self–powering is no longer possible thus the SMPS enters in a hiccup mode similar to the one described under the Overload condition.

In the SMPS stand–by mode the 3 distinct phases are:

The SWITCHING PHASE: Similar to the Overload mode. The current sense clamping level is reduced

according to the equation of the current sense section, page 5. The C.S. clamping level depends on the power to be delivered to the load during the SMPS stand–by mode. Every switching sequence ON/OFF is terminated by an OC as long as the secondary Zener diode voltage has not been reached. When the Zener voltage is reached the ON cycle is terminated by a true PWM action. The proper SWITCHING PHASE termination must correspond to a NOC condition. The LW latch stores this NOC status.

The LATCHED OFF PHASE: The MODE latch is set. The START-UP PHASE is similar to the Overload Mode. The MODE latch remains in its set status (Q=1).

The SWITCHING PHASE: The Stand-by signal is validated and the 200µA is sourced out of the Current Sense pin 2.

### • 4. Transition from Stand-by to Normal

The secondary reconfiguration is removed. The regulation on the low voltage secondary rail can no longer be achieved, thus at the end of the SWITCHING PHASE, no PWM condition can be encountered. The LW latch is reset.

At the next WORKING PHASE a NORMAL mode status takes place.

In order to become independent of the recovery time constant on the secondary side of the SMPS an additional reset input R2 is provided on the MODE latch. The condition Idemag<24µA corresponds to the activation of the secondary reconfiguration status. The R2 reset insures a return into the NORMAL mode following the first START–UP PHASE.

### **Pulsed Mode Duty Cycle Control**

During the sleep mode of the SMPS the switch S3 is closed and the control input pin 3 is connected to a 4.6V voltage source thru a  $500\Omega$  resistor. The discharge rate of the VCC capacitor is given by ICC-latch (device consumption during the LATCHED OFF phase) in addition to the current drawn out of the pin 3. Connecting a resistor between the Pin 3 and GND (RDPULSED) a programmable current is drawn from the VCC through pin 3. The duration of the LATCHED OFF phase is impacted by the presence of the resistor RDPULSED. The equation 3 shows the relation to the pin 3 current.

### **Pulsed Mode Phases**

Equations 1 through 8 define and predict the effective behavior during the PULSED MODE operation. The equations 6, 7, and 8 contain K, Y, and D factors. These factors are combinations of measured parameters. They appear in the parameter section "Kfactors for pulsed mode operation" page 4. In equations 3 through 8 the pin 3 current is the current defined in the above section "Pulsed Mode Duty Cycle Control".

### **EQUATION 1**

Start-up Phase Duration:

$$\mathbf{t_{start\!-\!up}} = \frac{\mathbf{C_{Vcc}} \times (\mathbf{V_{stup}} - \mathbf{UVLO2})}{\mathbf{I_{stup}}}$$

where:  $I_{stup}$  is the start–up current flowing through  $V_{CC}$  pin  $C_{VCC}$  is the  $V_{CC}$  capacitor value

### **EQUATION 2**

Switching Phase Duration:

$$t_{switch} = \frac{c_{Vcc} \times (V_{stup} - UVLO1)}{I_{ccS} + I_{G}}$$

where:  $I_{CCS}$  is the no load circuit consumption in switching phase  $I_G$  is the current consumed by the Power Switch

### **EQUATION 3**

Latched-off Phase Duration:

$$t_{latched-off} = \frac{C_{Vcc} \times (UVLO1 - UVLO2)}{I_{ccL} + I_{pin3}}$$

where:  $I_{CCL}$  is the latched off phase consumption  $I_{Din3}$  is the current drawn from pin3 adding a resistor

### **EQUATION 4**

Burst Mode Duty Cycle:

$$d_{BM} = \frac{t_{switch}}{t_{start-up} + t_{switch} + t_{latched-off}}$$

### **EQUATION 5**

$$\text{d}_{BM} = \frac{\frac{C_{\text{Vcc}} \times (\text{V}_{\text{stup}} - \text{UVLO1})}{\text{I}_{\text{ccS}} + \text{I}_{\text{G}}}}{\frac{C_{\text{Vcc}} \times (\text{V}_{\text{stup}} - \text{UVLO2})}{\text{I}_{\text{stup}}} + \frac{C_{\text{Vcc}} \times (\text{V}_{\text{stup}} - \text{UVLO1})}{\text{I}_{\text{ccS}} + \text{I}_{\text{G}}} + \frac{C_{\text{Vcc}} \times (\text{UVLO1} - \text{UVLO2})}{\text{I}_{\text{ccL}} + \text{I}_{\text{pin3}}}}$$

### **EQUATION 6**

$$d_{BM} = \frac{1}{1 + \left(k_{S/Stup} \times \frac{I_{ccS} + I_{G}}{I_{stup}}\right) + \left(k_{S/L} \times \frac{I_{ccS} + I_{G}}{I_{ccL} + I_{pin3}}\right)}$$

where:  $k_{S/Stup} = (V_{stup} - UVLO2)/(V_{stup} - UVLO1)$  $k_{S/L} = (UVLO1 - UVLO2)/(V_{stup} - UVLO1)$ 

### **EQUATION 7**

$$d_{BM} = \frac{1}{1 + \left[\frac{I_{CCS} + I_{G}}{I_{stup}} \times \left(k_{S/Stup} + \left(k_{S/L} \times \frac{I_{stup}}{I_{CcL} + I_{pin3}}\right)\right)\right]}$$

### **EQUATION 8**

$$d_{BM} = \frac{1}{1 + \left\{ \left( k1 + \frac{I_G}{I_{stup}} \right) \times \left( k_{S/Stup} + (k_{S/L} \times \frac{1}{k2 + \left( \frac{I_{pin3}}{I_{stup}} \right)}) \right) \right\}}$$

where:  $k1 = I_{CCS}/I_{Stup}$ 

 $k2 = I_{CCL}/I_{Stup}$ 

ks/stup = (V<sub>stup</sub>-UVLO2)/(V<sub>stup</sub>-UVLO1) ks/L = (UVLO1-UVLO2)/(V<sub>stup</sub>-UVLO1)

### PULSED MODE CURRENT SENSE CLAMPING LEVEL

Equations 9, 10, 11 and 12 allow the calculation of the Rcs value for the desired maximum current peak value during the SMPS stand-by mode.

### **EQUATION 9**

$$lpk_{stby} = \frac{V_{cs-th} - (R_{cs} \times I_{cs})}{R_{s}}$$

where: V<sub>CS-th</sub> is the CS comparator threshold

 $I_{CS}$  is the CS internal current source

Rs is the sensing resistor

R<sub>CS</sub> is the resistor connected between pin 2 and R<sub>S</sub>

### **EQUATION 10**

$$lpk_{stby} = V_{cs-th} \times \frac{1 - \left(R_{cs} \times \frac{I_{cs}}{V_{cs-th}}\right)}{R_{S}}$$

### **EQUATION 11**

$$lpk_{stby} = V_{cs-th} \times \frac{1 - (R_{cs} \times Y_{cs-stby})}{R_{s}}$$

where:  $Y_{CS-StbV} = I_{CS}/V_{CS-th}$ 

Taking into account the circuit propagation delay (δt<sub>CS</sub>) and the Power Switch reaction time (δt<sub>DS</sub>):

### **EQUATION 12**

$$lpk_{stby} = \left[ \begin{array}{c} V_{cs-th} \times \frac{1 - (R_{cs} \times Y_{cs-stby})}{R_{S}} \\ \end{array} \right] + \frac{V_{in} \times (\delta t_{cs} + \delta t_{ps})}{L_{p}}$$

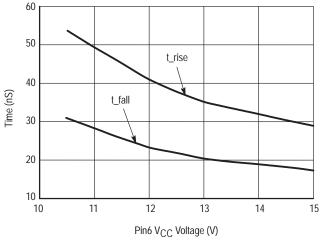


Figure 8. Output Switching Speed

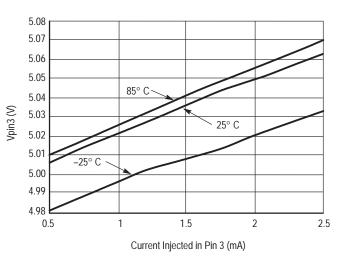


Figure 11. Vpin3 During the Working Period

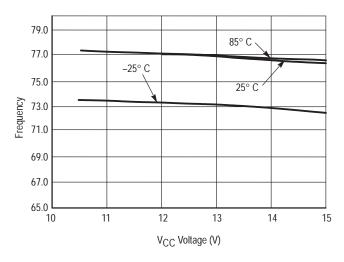


Figure 9. Frequency Stability

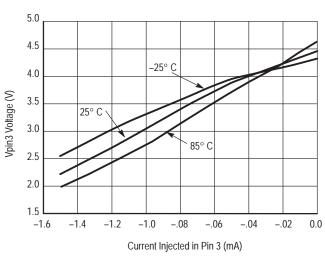


Figure 12. Vpin3 During the Latched Off Period

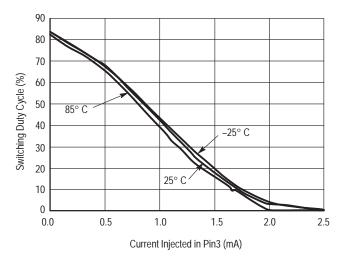


Figure 10. Duty Cycle Control

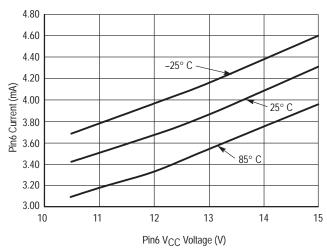


Figure 13. Device Consumption when Switching

Figure 14. High Voltage Current Source

Figure 15. Overload Burst Mode

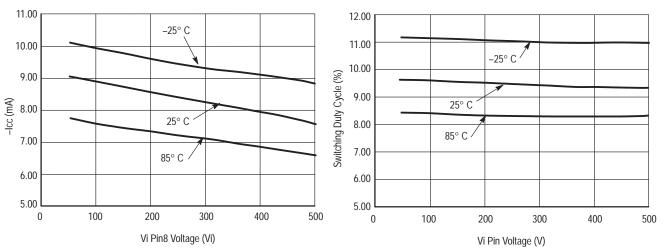
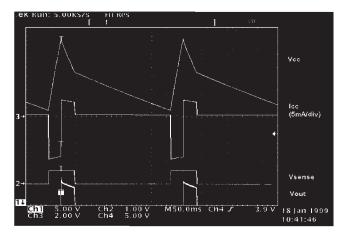


Figure 16. Hiccup Mode Waveforms



The data in Figure 15 corresponds to the waveform in Figure 16. The Figure 16 shows  $V_{CC}$ ,  $I_{CC}$ ,  $I_{Sense}$  (pin 2) and  $V_{out}$  (pin 5).  $V_{out}$  (pin 5) in fact shows the envelope of the output switching pulses. This mode corresponds to an overload condition.

The Figure 18 represents a complete power supply using the secondary reconfiguration.

The specification is as follows: Input source: 85Vac to 265Vac 3 Outputs 112V / 0.45A

16V / 1.5A 8V / 1A

Output power

Stand-by mode @ Pout = 300mW, 1.3W

80W

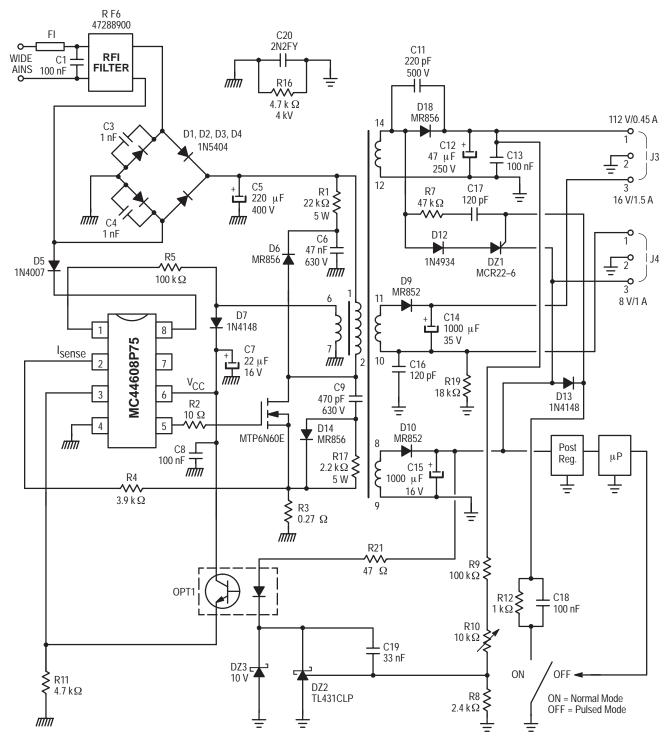


Figure 17. Typical Application

The secondary reconfiguration is activated by the  $\mu P$  through the switch. The dV/dt appearing on the high voltage winding (pins 14 of the transformer) at every TMOS switch off, produces a current spike through the series RC network R7, C17. According to the switch position this spike is either absorbed by the ground (switch closed) or flows into the thyristor gate (switch open) thus firing the MCR22–6. The closed position of the switch corresponds to the Pulsed Mode activation. In this secondary side SMPS status the high voltage winding (12–14) is connected through D12 and DZ1 to the 8V low voltage secondary rail. The voltages

applied to the secondary windings 12–14, 10–11 and 6–7 (Vaux) are thus divided by ratio N12–14 / N9–8 (number of turns of the winding 12–14 over number of turns of the winding 9–8). In this reconfigured status all the secondary voltages are lowered except the 8V one. The regulation during every pulsed or burst is performed by the zener diode DZ3 which value has to be choosen higher than the normal mode regulation level. This working mode creates a voltage ripple on the 8V rail which generally must be post regulated for the microProcessor supply.

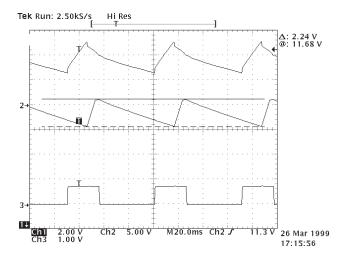


Figure 18. SMPS Pulsed Mode

The Figure 18 shows the SMPS behavior while working in the reconfigured mode. The top curve represents the  $V_{CC}$  voltage (pin 6 of the MC44608). The middle curve represents the 8V rail. The regulation is taking place at 11.68V. On the bottom curve the pin 2 voltage is shown. This voltage represents the current sense signal. The pin 2 voltage

is the result of the 200µA current source activated during the start—up phase and also during the working phase which flows through the R4 resistor. The used high resolution mode of the oscilloscope does not allow to show the effective ton current flowing in the sensing resistor R11.

### **PACKAGE DIMENSIONS**

### DIP-8 **P SUFFIX** PLASTIC PACKAGE CASE 626-05

ISSUE K

-B-NOTE 2 -T-SEATING PLANE G ⊕ Ø 0.13 (0.005) M T A M B M

- NOTES:
  1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  2. PACKAGE CONTOUR OPTIONAL (ROUND OR SOURCE CORNERS).
  3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

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